

JFP PP6 Universal Die Bonder



The machines which require minimal training to operate

MADE IN FRANCE

- ▶ **XYZ Automated Process**
- ▶ **Multiple Process**



Click the following links to view :
[Eutectic AuSi with JFPmicrotechnic PP6 - YouTube](#)

- The Die Bonder model PP6 is the most versatile semi-automatic Flip-Chip Platform.
- Designed for accurate placement of delicate devices on substrate.
- It achieves high accuracy placement using high quality optical device.
- The machine provides for single collet vacuum pick and place of dies from waffle pack, wafer, Gel-Pak or bulk die media and features adjustable and repeatable subsonic scrub.
- All process capability.
- Flip Vision alignment for Small and large devices.
- A full automated die bonding sequence with according epoxy pattern are programmable Off-Line... a simple matrix or multiple locations as well.
- The PP6 is designed to be external vibration free.
- The PP6 is user friendly, flexible, and requires minimum training to operate.

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APPLICATIONS/TECHNOLOGIES

- **Pick & Place**
- **Flip Chip Assembly**
- **Very Small & Large Components**
- **MEMS,MMICS, IR sensor, opto, 2,5D & 3D IC Packaging laser diode bar Assembly...**

Project Bar Assy, Click the following links to view
<https://www.youtube.com/watch?v=AmWTrRUrIFe>

DIE & SUBSTRATE

- Minimum die size 70*70µm
- Maximum die size 40*40 mm
- Input carrier:
Gel/Waffle Pack, tray, wafer eject/sorter
- Maximum substrate size 400*250 mm
- Long laser bars, not limited

VISION SYSTEM

- Video Microscope UHD cameras, 18Mp
- **Full std** FOV = 2,7mm,
Std Pixel resolution 1p = 0,55µm
Other magnification (FOV) on request
- Digital Zoom x 10
- Monitor : TFT 22"
- Led Lighting, co-axial and oblique

MOTORIZED XY TABLES

- Motorized X 260mm, Y 120mm,
step resolution 0,23µm
Display Unit : 1µm
- Joystick control

WORKHOLDER

- Compatible for any package up to 100mm Thick.
- High accuracy motorized Centering Stage
- Fine rotary stage for precise alignment
- Customized

FEATURES

Placement accuracy <+/- 1µm
Vibration free
Product speed 10-50 upon Process

- **Thermo-sonic die bonding**
- **Soldering/Reflow**
- **Eutectic thermo cycle**
- **Wafer sorter up to 8"**
- **Dispenser for Epoxy & solder paste Stamping...**

PARAMETERS & DISPLAY

- Friendly Graphic user Interface, GUI Menu
- Programmable force : up to 700 gr
- Programmable bond time
- Programmable scrub
- Programmable temperature ramp-up
- Programmable sequence

ALIGNMENT MODE

- Direct placement of Face-up devices
- 2 references points for auto-centering placement
- Indexed Pick and multi-Placement mode

OPTIONS

- Flip Chip alignment, Face down
- Eutectic Chuck,+ Gas environment 25°C to 450°C
- Formic Acid Process
- Dispensing / Stamping
- Additional Force: up to 5 or 15 kg
- Sorter: Eject system for wafer
- Hot Gas Gun
- Heated Tool 400°C
- UV Insolator

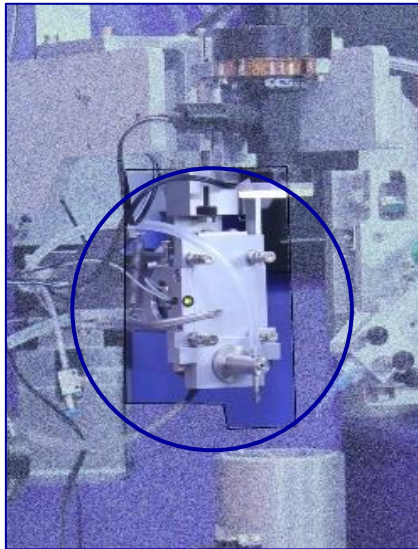
TECHNICAL SPECIFICATION

Power	230VAC-1kwatt
Dimensions	650*820*1450mm
Weight	90kg
Compressed Air	6 bar

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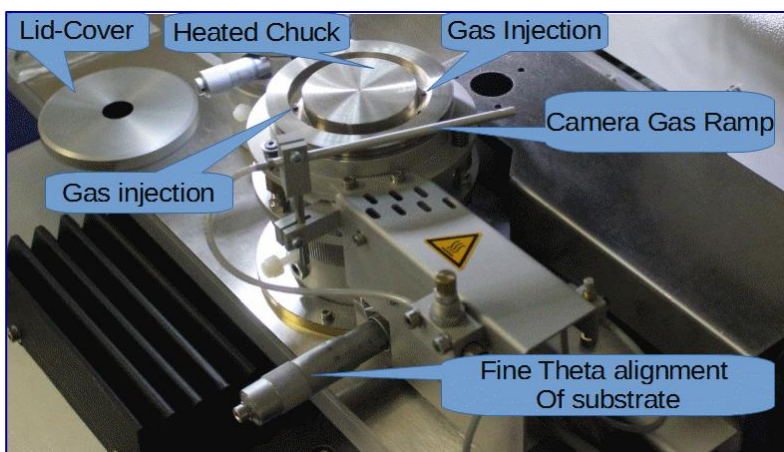
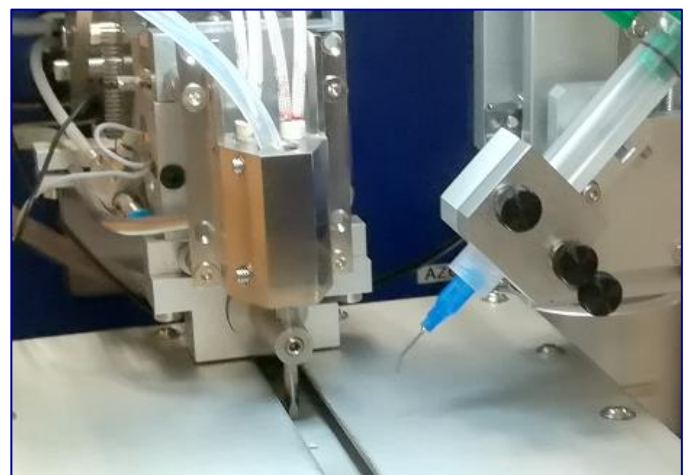
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Ultrasonic head
High power

**Heated Tool with
extra force 15kg**

- +Standard small Shank (1/8)
- +Large Shank (8mm) Capability for very large chips



Eutectic Station

- +Temp. 25°C to 450°C
- + Cover (Open lid)
- + Gas environment
- + Cooling inside
- + Size 50mm and more
- + Programming Profile
- + Real Time display

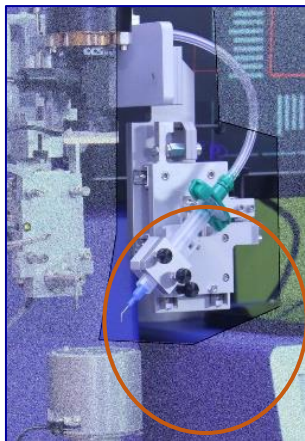
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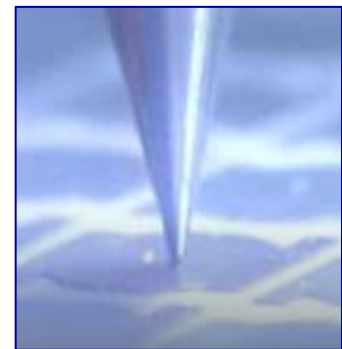
Dispensing head for Epoxy & Solder paste

Programmable Patterns



Rotary stamping Unit

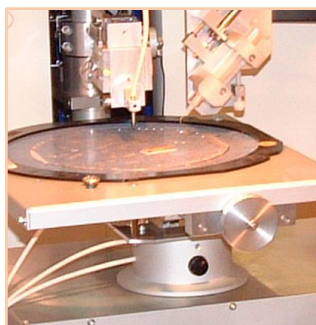
Glue deposit for small geometry



Stamping Tool

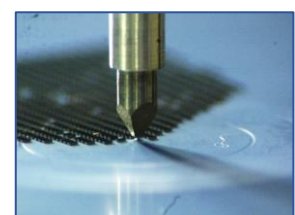
Flip system

Overlay Area Of Interest
Multipoint alignment



Wafer Die-Ejector

- Small chips 150μ
- Laser diodes
- Laser bars



Option Process Camera
For Life View